

LOCTITE ABLESTIK NCF 220

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PRODUCT DESCRIPTION

LOCTITE ABLESTIK NCF 220 provides the following product characteristics:

Ta alamata ana	BMI
Technology	BIVII
Appearance	Transparent yellow film
Product Benefits	Enable fine pitch, narrow gap Cu Pillar
Cure	Heat cure
Application	Semiconductor, Wafer Applied Underfill
Typical Package Application	TSV interconnect
Typical Applications	Thermal Compression Bonding

LOCTITE ABLESTIK NCF 220 transparent film is specially formulated for Pb free, low κ , thin gap, large and thin die used in advance flip chip applications. This material is suitable for die to die, die to wafer (TSV) or die to substrate applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Shelf Life @ 5 °C, days	180
Flash Point - See SDS	

TYPICAL PROCESS DATA

Lamination

Vacuum Time, seconds	10
Pressure, MPa	0.5
Pressure Time, seconds	60
Temperature, °C	50 to 55

Thermal Compression Bonding

Sample used: 7.3 X 7.3 x 0.15 mm SiN passivat	ion
Stage Temperature, °C	100
Contact Temperature, °C	130
Search speed, mm/sec	1
Bonding Time (Total), seconds	<4
Bonding Force (depending on die size and	35
bump count), N	
Peak Temperature, °C	260

The above thermal compression profile and post cure condition are guideline recommendations. These conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL CURING PERFORMANCE

Recommended Cure Schedule

30 minutes ramp to 175°C, hold 2 hours @ 175 °C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Coefficient of Thermal Evnansion :

Physical Properties

Coemcient of Thermal Expansion.	
Below Tg, ppm/°C	36
Above Tg, ppm/°C	154
Glass Transition Temperature, °C	123
Weight Loss, TGA @ 250 °C, %	1.2

DMA Modulus:

Divin (integration :		
@ 25°C	N/mm² (psi)	6,400 (928,000)
@ 250°C	N/mm² (psi)	188 (27,300)
DSC (Differential Scanning Calorimetry):		
On-set temperature, °C		160

On-set temperature, °C
Peak tempertature

Extractable Ionic Content, ppm:	
Sodium (Na+)	<10
Potassium (K+)	<10
Chloride (Cl-)	<10

Moisture Absorption 24 hrs @ 85°C/85% RH, wt % 1.2

TYPICAL PERFORMANCE OF CURED MATERIAL

Hot Die Shear Strength @ 260 °C:

3. 0		
3 x 3 mm SiN die on BT substrate	N/mm²	6.8
	(nsi)	(986)

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

THAWING:

 Allow container to reach room temperature before use, normally 30 minutes.



DIRECTIONS FOR USE

 The surfaces on which the adhesive has to be applied should be clean, dry and free from all dust.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -5 to +5°C. Storage below -5°C or above 25°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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